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Cypress Semiconductor Product Qualification Report

QTP# 045202 VERSION*D
March, 2015

1 Meg MoBL SRAM Family	
R95LD-3R, FAB 4	
CY62125EV MoBL®	1-Mbit Static RAM Die
CY62126EV18 MoBL®	1-Mbit (64K x 16) Static RAM
CY62126EV30 MoBL®	1-Mbit (64K x 16) Static RAM
CY62127EV18 MoBL2™	1-Mbit (64K x 16) Static RAM
CY62127EV30 MoBL®	1-Mbit (64K x 16) Static RAM
CY62128E MoBL®	1-Mbit (128K x 8) Static RAM
CY62128EV30 MoBL®	1-Mbit (128K x 8) Static RAM
CY62256EV18 MoBL®	256-KBIT (32K x 8) Static RAM

FOR ANY QUESTIONS ON THIS REPORT, PLEASE CONTACT
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PRODUCT QUALIFICATION HISTORY

QTP Number	Description of Qualification Purpose	Date
054302	R95LD-3R, Fab 4 and New Device CY7C62xxx (4Meg) MoBL Product Family	Dec 05
045202	R95LD-3R, Fab 4 and New Device CY62xxx (1Meg) MoBL Product Family	Mar 06
113601	Qualification of R95LD-3R 256K Micropower Part Bond Option of 1M in 28SNC Package, Fabricated in CMI	Sep 11
134510	Qualify polyimide mask to qualified Industrial 1 Meg MoBL SRAM, R95LD-3R Technology at Fab 4	Nov 13

PRODUCT DESCRIPTION (for qualification)	
Qualification Purpose: Qualify CY62xxx (1 Mbit) MoBL product family in qualified technology R95LD-3R, Fab 4	
Marketing Part #:	CY62125EV/ CY62126EV18/CY62126EV30/CY62127EV18/CY62127EV30/ CY62128E/CY62128EV30/CY62256EV18
Device Description:	1.8V, 3V, 5V 1Meg MoBL SRAM
Cypress Division:	Cypress Semiconductor Corporation –Memory Products Division (MPD)

TECHNOLOGY/FAB PROCESS DESCRIPTION			
Number of Metal Layers:	2	Metal Composition:	Metal 1: 100Å Ti / 3200Å Al / 300Å TiW Metal 2: 150Å Ti / 8000Å Al / 300Å TiW
Passivation Type and Thickness:	1000Å Oxide TEOS / 9000Å Nitride		
Generic Process Technology/Design Rule (μ-drawn):	CMOS, Double Metal, 0.09μm		
Gate Oxide Material/Thickness (MOS):	28Å		
Name/Location of Die Fab (prime) Facility:	Cypress Semiconductor – Bloomington, MN		
Die Fab Line ID/Wafer Process ID:	Fab4/R95LD-3RP		

PACKAGE AVAILABILITY

PACKAGE	ASSEMBLY SITE FACILITY
48-Ball VFBGA	ASE- Taiwan (G), CML-RA
44-Lead TSOP II	JCET-China (JT)
32-Lead TSOP I	OSE-Taiwan (T), CML-RA
32-Lead RTSOP I/STSOP I	OSE- Taiwan (T), CML-RA
32-Lead SOIC	JCET-China (JT)
28-Lead TSOP I	JCET-China (JT)
28-Lead RTSOP I	JCET-China (JT)
28-Lead SNC	JCET-China (JT)
28-Lead PDIP	MMT-Thailand (X)

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION

Package Designation:	ZW44
Package Outline, Type, or Name:	44-Pin Thin Small Outlined Packages (Type II)
Mold Compound Name/Manufacturer:	Hitachi CEL9200
Mold Compound Flammability Rating:	V-O per UL94
Mold Compound Alpha Emission Rate:	0.001c/cm2-h
Oxygen Rating Index:	N/A
Substrate Material:	Copper
Lead Finish, Composition / Thickness:	NiPdAu
Die Backside Preparation Method/Metallization:	Backgrind
Die Separation Method:	100% Saw Through
Die Attach Supplier:	Dexter
Die Attach Material:	QMI-509
Die Attach Method:	Epoxy
Bond Diagram Designation:	10-06259
Wire Bond Method:	Thermosonic
Wire Material/Size:	Au. 0.8mil
Thermal Resistance Theta JA °C/W:	27.83° C/W
Package Cross Section Yes/No:	N/A
Assembly Process Flow:	001-64160
Name/Location of Assembly (prime) facility:	Cypress Philippines (CML-R)
MSL Level	3
Reflow Profile	260C

ELECTRICAL TEST / FINISH DESCRIPTION

Test Location:	Cypress Philippines (CML-R)
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Note: Please contact a Cypress Representative for other package availability.

RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENTS

Stress/Test	Test Condition (Temp/Bias)	Result P/F
High Temperature Operating Life Early Failure Rate	AEC-Q100-008 and JESD22-A108 Dynamic Operating Condition, Vcc Max = 1.85V, 125°C	P
High Temperature Operating Life Latent Failure Rate	JESD22-A108 Dynamic Operating Condition, Vcc Max = 1.85V, 150°C, 125°C	P
Long Life Verification	JESD22-A108 Dynamic Operating Condition, Vcc = 1.85V, 150°C	P
High Temperature Steady State Life	JESD22-A108 Static Operating Condition, Vcc Max = 1.75V, 125°C	P
Low Temperature Operating Life	JESD22-A108 Dynamic Operating Condition, Vcc = 2.0V, -30°C	P
High Accelerated Saturation Test (HAST)	JESD22-A110, 130°C, 3.63V/5.5V, 85%RH JESD22-A110, 110°C, 1.85V, 85%RH Precondition: JESD22 Moisture Sensitivity MSL 3 192 Hrs, 30°C/60%RH+ Reflow, 260°C+0, -5°C	P
Temperature Cycle	MIL-STD-883, Method 1010, Condition C, -65°C to 150°C Precondition: JESD22 Moisture Sensitivity MSL 3 192 Hrs, 30°C/60%RH+ Reflow, 260°C+0, -5°C	P
Pressure Cooker	JESD22-A102, 121°C, 100%RH, 15 Psig Precondition: JESD22 Moisture Sensitivity MSL 3 192 Hrs, 30°C/60%RH+ Reflow, 260°C+0, -5°C	P
High Temperature Storage	JESD22-A103, 150°C, no bias	P
Electrostatic Discharge Human Body Model (ESD-HBM)	2,200V MIL-STD-883, Method 3015.7	P
Electrostatic Discharge Human Body Model (ESD-HBM)	2,200V JEDEC EIA/JESD22-A114	P
Electrostatic Discharge Charge Device Model (ESD-CDM)	500V JESD22-A101	P
Alpha Particle Sensitivity	JESD89	P
Age Bond Strength	200°C, 4HRS MIL-STD-883, Method 883-2011	P
Acoustic Microscopy	JEDEC JSTD-020	P
Dynamic Latch Up	JESD78	P
Static Latch Up	125C, \pm 140/200/300mA JESD78	P

RELIABILITY FAILURE RATE SUMMARY

Stress/Test	Device Tested/ Device Hours	# Fails	Activation Energy	Thermal AF ³	Failure Rate
High Temperature Operating Life Early Failure Rate	3,488 Devices	0	N/A	N/A	0 PPM
High Temperature Operating Life ^{1,2} Long Term Failure Rate	274,000 DHRs	0	0.7	170	24 FIT

¹ Assuming an ambient temperature of 55°C and a junction temperature rise of 15°C.

² Chi-squared 60% estimations used to calculate the failure rate.

³ Thermal Acceleration Factor is calculated from the Arrhenius equation

$$AF = \exp \left[\frac{E_A}{k} \left[\frac{1}{T_2} - \frac{1}{T_1} \right] \right]$$

where:

E_A = The Activation Energy of the defect mechanism.

K = Boltzmann's constant = 8.62×10^{-5} eV/Kelvin.

T_1 is the junction temperature of the device under stress and T_2 is the junction temperature of the device at use conditions.

Reliability Test Data

QTP #:054302

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
STRESS: ACOUSTIC-MSL3							
CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	COMP	15	0	
CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	COMP	15	0	
CY62147EV30LL (7C62147F)	4447261	610506302N	CML-R	COMP	15	0	
STRESS: AGE BOND STRENGTH							
CY62147EV30LL (7C62147F)	4514985	610527600	CML-R	COMP	10	0	
CY62136EV30LL (7C62136F)	4516742	610537839	CML-R	COMP	10	0	
CY62147EV30LL (7C62147F)	4516646	610527599	CML-R	COMP	10	0	
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 125C, 1.85V, Vcc Max (Core)							
CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	96	679	0	
CY62147EV30LL (7C62147F)	4527847	610558767	CML-R	96	4031	0	
CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	96	1711	0	
CY62147EV30LL (7C62147F)	4447261	610506302N	CML-R	96	917	1	Single Bit (Non-visual)
STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 150C, 1.85V, Vcc Max (Core)							
CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	80	400	0	
CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	500	400	1	Blocked contact at Poly
CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	80	400	0	
CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	500	400	0	
CY62147EV30LL (7C62147F)	4447261	610506302N	CML-R	80	400	0	
CY62147EV30LL (7C62147F)	4447261	610506302N	CML-R	500	400	0	
STRESS: LONG LIFE VERIFICATION, 150C, 1.85V, Vcc Max (Core)							
CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	1000	393	0	
STRESS: HIGH TEMPERATURE STEADY STATE LIFE, 125C, 1.75V, Vcc Max							
CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	168	76	0	
CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	336	75	0	
STRESS: LOW TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, -30C, 2.0V, Vcc							
CY62147EV30LL (7C62147F)	4447261	610506302N	CML-R	500	45	0	
STRESS: HIGH TEMPERATURE STORAGE							
CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	500	45	0	
CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	1000	45	0	

Reliability Test Data

QTP #:054302

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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STRESS: ESD-CHARGE DEVICE MODEL, 500V

CY62147EV30LL (7C62147F)	4527847	610548767	CML-R	COMP	9	0	
CY62148EV30LL (7C62148F)	4527847	610548491	TAIWN-G	COMP	9	0	
CY62148EV30LL (7C62148F)	4527847	610550592	CML-RA	COMP	9	0	
CY62147EV30LL (7C62147F)	4516646	610527599	CML-R	COMP	9	0	
CY62147EV30LL (7C62147F)	4514985	610527600	CML-R	COMP	9	0	
CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	COMP	9	0	

STRESS: ESD-HUMAN BODY CIRCUIT PER JEDEC EIA/JESD22-A114, 2,200V

CY62147EV30LL (7C62147F)	4527847	610548767	CML-R	COMP	9	0	
CY62148EV30LL (7C62148F)	4527847	610548491	TAIWN-G	COMP	9	0	
CY62148EV30LL (7C62148F)	4527847	610551587	CML-R	COMP	9	0	
CY62148EV30LL (7C62148F)	4527847	610550592	CML-RA	COMP	9	0	
CY62147EV30LL (7C62147F)	4516646	610527599	CML-R	COMP	9	0	
CY62147EV30LL (7C62147F)	4514985	610527600	CML-R	COMP	9	0	
CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	COMP	9	0	

STRESS: ESD-HUMAN BODY CIRCUIT PER MIL STD 883, METHOD 3015, 2,200V

CY62147EV30LL (7C62147F)	4527847	610548767	CML-R	COMP	3	0	
CY62148EV30LL (7C62148F)	4527847	610548491	TAIWN-G	COMP	3	0	
CY62148EV30LL (7C62148F)	4527847	610551587	CML-R	COMP	3	0	
CY62148EV30LL (7C62148F)	4527847	610550592	CML-RA	COMP	3	0	
CY62147EV30LL (7C62147F)	4516646	610527599	CML-R	COMP	3	0	
CY62147EV30LL (7C62147F)	4514985	610527600	CML-R	COMP	3	0	
CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	COMP	3	0	

STRESS: HI-ACCEL SATURATION TEST, 130C, 85%RH, 3.63V, PRE COND 192 HR 30C/60%RH, MSL3

CY62137EV30LL (7C62137F)	4516742	610539321	CML-R	128	45	0	
CY62137EV30LL (7C62137F)	4516742	610539321	CML-R	256	45	0	
CY62137EV30LL (7C62137F)	4516742	610539321	CML-R	128	54	0	

STRESS: HI-ACCEL SATURATION TEST, 130C, 85%RH, 5.5V, PRE COND 192 HR 30C/60%RH, MSL3

CY62147EV30LL (7C62147F)	4527847	610558767	CML-R	128	45	0	
CY62147EV30LL (7C62147F)	4527847	610558767	CML-R	264	45	0	

Reliability Test Data

QTP #:054302

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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STRESS: DYNAMIC LATCH-UP TESTING, 9.0V

CY62147EV30LL (7C62147F)	4438656	610461414	TAIWN-G	COMP	3	0	
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STRESS: STATIC LATCH-UP TESTING, 125C, 6.5V, +/-300mA

CY62147EV30LL (7C62147F)	4514985	610527600	CML-R	COMP	3	0	
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STRESS: STATIC LATCH-UP TESTING, 125C, 10V, +/-300mA

CY62147EV30LL (7C62147F)	4527847	610548767	CML-R	COMP	3	0	
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STRESS: STATIC LATCH-UP TESTING, 125C, 9.5V, +/-300mA

CY62147EV30LL (7C62147F)	4516646	610527599	CML-R	COMP	3	0	
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CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	COMP	3	0	
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STRESS: STATIC LATCH-UP TESTING, 125C, 8.5V, +/-200mA

CY62148EV30LL (7C62148F)	4527847	610548491	TAIWN-G	COMP	3	0	
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CY62148EV30LL (7C62148F)	4527847	610551587	CML-R	COMP	3	0	
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CY62148EV30LL (7C62148F)	4527847	610550592	CML-RA	COMP	3	0	
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STRESS: PRESSURE COOKER TEST, 121C, 100%RH, 15 Psig, PRE COND 192 HR 30C/60%RH, MSL3

CY62147EV30LL (7C62147F)	4516742	610537714	CML-R	168	50	0	
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CY62147EV30LL (7C62147F)	4516742	610537714	CML-R	288	50	0	
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CY62147EV30LL (7C62147F)	4516646	610537739	CML-R	168	50	0	
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CY62147EV30LL (7C62147F)	4516646	610537739	CML-R	288	50	0	
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CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	168	50	0	
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STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH, MSL3

CY62147EV30LL (7C62147F)	4438656	610461414	CML-RA	300	42	0	
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CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	300	49	0	
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CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	500	48	0	
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CY62147EV30LL (7C62147F)	4519690	610533058	CML-RA	1000	46	0	
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CY62147EV30LL (7C62147F)	4447261	610506302N	CML-R	300	45	0	
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CY62147EV30LL (7C62147F)	4447261	610506302N	CML-R	500	44	0	
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CY62147EV30LL (7C62147F)	4447261	610506302N	CML-R	1000	44	0	
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Reliability Test Data

QTP #: 045202

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 125C, 1.85V, Vcc Max (Core)

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	96	3488	0	
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STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 150C, 1.85V, Vcc Max (Core)

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	80	399	0	
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CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	500	396	0	
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STRESS: ESD-HUMAN BODY CIRCUIT PER JEDEC EIA/JESD22-A114, 2,200V

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	COMP	9	0	
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CY6264ELL (7C62608F)	4538636	610602821	CML-R	COMP	9	0	
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CY62128ELL (7C62628F)	4538636	610602218	TAIWN-T	COMP	9	0	
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STRESS: ESD-HUMAN BODY CIRCUIT PER MIL STD 883, METHOD 3015, 2,200V

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	COMP	3	0	
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CY6264ELL (7C62608F)	4538636	610602821	CML-R	COMP	3	0	
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CY62128ELL (7C62628F)	4538636	610602218	TAIWN-T	COMP	3	0	
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STRESS: ESD-CHARGE DEVICE MODEL, 500V

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	COMP	9	0	
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CY6264ELL (7C62608F)	4538636	610602821	CML-R	COMP	9	0	
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CY62128ELL (7C62628F)	4538636	610607235	CML-R	COMP	9	0	
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CY62128ELL (7C62628F)	4538636	610600869	CML-R	COMP	9	0	
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CY62256ELL (7C62618F)	4538636	610604368	CML-R	COMP	9	0	
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CY62127EV30LL (7C62127F)	4544420	610606707	TAIWN-G	COMP	9	0	
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CY62128ELL (7C62628F)	4538636	610602218	TAIWN-T	COMP	9	0	
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STRESS: ALPHA PARTICLE SENSITIVITY

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	COMP	5	0	
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STRESS: DYNAMIC LATCH-UP TESTING, 9.0V

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	COMP	3	0	
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STRESS: STATIC LATCH-UP TESTING, 125C, 6.5V, +/-200mA

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	COMP	3	0	
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STRESS: STATIC LATCH-UP TESTING, 125C, 8.5V, +/-200mA

CY6264ELL (7C62608F)	4538636	610602821	CML-R	COMP	3	0	
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CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	COMP	3	0	
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CY62128ELL (7C62628F)	4538636	610602218	TAIWN-T	COMP	3	0	
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Reliability Test Data
QTP #: 045202

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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STRESS: PRESSURE COOKER TEST, 121C, 100%RH, 15 Psig, PRE COND 192 HR 30C/60%RH, MSL3

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	168	50	0	
CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	288	50	0	

STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH, MSL3

CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	300	49	0	
CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	500	49	0	
CY62127EV30LL (7C62127F)	4538636	610558732	CML-R	1000	49	0	

Reliability Test Data

QTP #: 113601

<i>Device</i>	<i>Fab Lot #</i>	<i>Assy Lot #</i>	<i>Assy Loc</i>	<i>Duration</i>	<i>Samp</i>	<i>Rej</i>	<i>Failure Mechanism</i>
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STRESS: ESD-HUMAN BODY CIRCUIT PER JEDEC EIA/JESD22-A114, 2,200V

CY62256EV18LL (7C62256F)	4117680	611135328	CML-R	COMP	8	0	
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STRESS: ESD-CHARGE DEVICE MODEL, 500V

CY62256EV18LL (7C62256F)	4117680	611135328	CML-R	COMP	9	0	
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STRESS: STATIC LATCH-UP TESTING, 125C, 3.37V, +/-140mA

CY62256EV18LL (7C62256F)	4117680	611135328	CML-R	COMP	6	0	
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Reliability Test Data

QTP #: 134510

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 125C, 1.85V, Vcc Max (Core)

CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	168	76	0	
CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	1000	76	0	

STRESS: TC COND. C -65C TO 150C, PRE COND 192 HRS 30C/60%RH, MSL3

CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	500	77	0	
CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	1000	76	0	

STRESS: PRESSURE COOKER TEST, 121C, 100%RH, 15 Psig, PRE COND 192 HR 30C/60%RH, MSL3

CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	96	76	0	
CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	168	65	0	

STRESS: HI-ACCEL SATURATION TEST, 110C, 85%RH, 1.85V, PRE COND 192 HR 30C/60%RH, MSL3

CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	128	77	0	
CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	264	77	0	

STRESS: HIGH TEMPERATURE STORAGE

CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	1000	77	0	
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STRESS: INTERNAL VISUAL

CY62157EV30LL (7C62157F)	4229219	611238363	CML-RA	COMP	5	0	
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STRESS: SORT YIELD

7C62155FC	VARIOUS	NA	NA	COMP	EQUIVALENT		
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STRESS: E-TEST YIELD

7C62155FC	VARIOUS	NA	NA	COMP	EQUIVALENT		
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Document History Page

Document Title: QTP 045202: 1 MEG MOBL SRAM FAMILY, R95LD-3R, FAB 4
Document Number: 001-76404

Rev.	ECN No.	Orig. of Change	Description of Change
**	3538122	NSR	Initial Spec Release (Previous Rev 3.0 Qual report reference in memo LGQ-727). Added CY62256EV18 256-KBIT device in the Title Page. Added QTP 113601 data in the Qualification History page and in the QTP stress data. Removed the Omedata Indonesia in assembly site facilities.
*A	3926247	JYF	Removed Version 4.0 in QTP# 045202 title page; Updated Assembly Site Facility Table: <ul style="list-style-type: none"> - Deleted Phil-M - Deleted CML-R and replaced with JCET-China (JT) - Corrected typo error on ASE assy site code, from ASE-T to ASE- Taiwan (G) - Updated assy sites to include both code and location Deleted obsolete referenced spec 11-20047 in Major Package Information Table and replaced with 001-64160; Updated Reliability Tests Performed Table: <ul style="list-style-type: none"> - Deleted "3IR" in reflow step of HAST, PCT and TCT - Deleted Cypress' referenced specs and replaced with industry standards. - Deleted Current Density (internal requirement only)
*B	4185173	JYF	Added polyimide qualification data.
*C	4311032	JYF	Alignment of QTP title page to standard template.
*D	4692962	JYF	Added CY62126EV18 MPN in QTP coverage; Aligned MPNs in Product Description table with MPNs in QTP title page; Added 110C HAST condition in Reliability Tests Performed table.

Distribution: WEB

Posting: None